

Board model		CPB904	CPB906	CPB907	CPC1302	CPC1310	CPC1311
Compliance with the standard		ETX	F-COM	COM Express mini Type 10	COM Express Basic Type 6	COM Express Basic Type 2	COM Express mini Type 10
Overall dimensions		114,0 × 95,0 × 14 mm	65,2 × 40,2 × 10,5 mm	84 × 55 × 15 mm	125 x 95 × 23,4 mm (taking into account heat-removal plate and racks)	125 x 95 × 23,4 mm (taking into account heat-removal plate and racks)	84×55×15 mm
CPU		AMD Geode™ LX800 500 MHz	Vortex86DX	Intel Atom E6xxT	Intel Core i7-5850EQ/i5-4422E	Intel Atom N450/D510	Intel Atom E38xx
RAM		DDR, 333 MHz 256 MB (soldered)	DDR2 SDRAM 256 MB (soldered)	DDR2 SDRAM 1 GB (soldered)	DDR3L-1600 SDRAM up to 8 GB with ECC support (soldered)	DDR2 SDRAM 667 MHz 1 GB (soldered)	DDR3L-1066/1333 SDRAM up to 4 GB with ECC support (soldered)
Graphics subsystem	Type	Soldered	No	Integrated into CPU	Integrated into CPU	Integrated into CPU	Integrated into CPU
	Interfaces	VGA up to 1920×1440 (85 GHz 32 bit), LCD up to 1024×768 (60 GHz 24 bit)	No	LVDS up to 1280 x 768 (60 Hz) SDVO up to 1920 x 1080 (50 Hz)	1×LVDS Channel (24 bit, 1920×1200, 60 Hz 3×DDI 4096×2304, 60 Hz 1×VGA CRT 1920×2000, 60 Hz	VGA up to 1400x1050 60 Hz (N450) and 2048x1536 60 Hz (D510)) LVDS up to 1280x800 60 Hz (N450) and 1366x768 60 Hz (D510), (18 bit)	LVDS up to 1600×1200 (60 Hz) DDIO, eDP up to 2560×1600 (60 Hz)
	Number of independent displays	1	-	2	3	2	2
Storage subsystem interfaces	IDE	1×IDE	1×IDE, NAND Flash-drive 1 GB, soldered	No	-	1×IDE	-
	SATA	No	No	2×SATA II, NAND Flash-drive 4 GB, soldered	4×SATA III	2×SATA II, NAND Flash-drive 4 GB, soldered	2×SATA II

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Communication interfaces	Removable storage devices	No	No	1×MicroSD	16 GB	No	-
	ISA	16 bit	8 bit	No	-	16 bit (via additional connector)	-
	PCI	32 bit	32 bit	No	-	32 bit	-
	PCI Express	No	No	3×PCIe x1	1×PCIe x16 Gen3 7×PCIe x1 Gen2	4×PCIe x1	3(4) × PCIe x1
	Ethernet	1×Fast Ethernet	1×Fast Ethernet	1×Gigabit Ethernet	×Gigabit Ethernet	2×Gigabit Ethernet	1×Gigabit Ethernet
	USB	4×USB 2.0	2×USB 2.0	7×USB 2.0	8×USB 2.0, 4×USB 3.0	8×USB 2.0	5×USB 2.0; 1×USB 3.0
	COM-ports	3×RS-232	2×RS-232	1×RS-232, 1×RS-232 or 1×CAN	2×RS-232	No	1×RS-232, 1×RS-232 or 1×CAN
	Digital I/O channels	No	6 x digital I/O channels 2x channels of integrated address decoder (addressable I/O and memory space)	8 x programmable I/O channels	4 x programmable I/O channels	8 x I/O channels, individually programmable. 8 x additional I/O channels on additional connector	4 x programmable I/O channels
Others	PS/2, 1×LPT	PS/2, 1×LPC, 1×I2C	1×LPC, 1×SPI, 1×I2C, 1×SMBus	1×SPI, 1×LPC, 1×I2C, 1×SMBus, HD Audio, Speaker Out	PS/2, LPT, 1×LPC, 1×I2C, 1×SMBus	1×LPC, 1×SPI, 1×I2C, 1×SMBus	
Service capabilities	1 watchdog timer, real-time clock, hardware monitor, HD Audio controller	2 watchdog timers, real-time clock, external reset	1 watchdog timer, real-time clock, hardware monitor, digital accelerometer, digital barometer, audio microphone, audio input/output	1 watchdog timer, real-time clock, console I/O, Monitor of 7 power supply voltages, PCB temperature monitor	2 watchdog timers, real-time clock, hardware monitor, HD Audio controller	1 watchdog timer, real-time clock, console I/O	

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Support of OS	MS-DOS, Windows XPe, Linux 2.6, QNX 6.3x, QNX 4.25	FDOS, MS-DOS 6.22, Windows CE 5, Linux 2.6, QNX 6.4x	MS-DOS, Windows CE 6.0, XPe, 7, Linux 2.6, QNX 6.5.x	MS DOS 6.22, Windows 7/8, Linux 3.8.x, QNX 6.x	FDOS, Windows XPe, Linux 2.6, QNX 6.5	MS DOS 6.22, Windows ES7, Windows ES8, Linux 2.6, QNX 6.5
Power supply	+5V	+5V	+4.75...+20.0 V	+8...+14 V	+5...+14 V	+4,75...+20 V
Target power consumption *	5 W	2,25 W	up to 9 W	From 38 to 51 W, depending on the version	Up to 14,5 W, depending on the version	From 8 up to 16 W depending on the version
Vibration/Shock resistance	5g/100g	5g/100g	5g/100g	2g/50g	2g/50g	5g/100g
MTBF (GOST 15150-69)	200000 hours	320000 hours	200000 hours	100 000 hours	180000 hours	200 000hours
Operating temperature range**	-40...+85°C	-40...+85°C	-40...+85°C	-40...+85°C	-40...+85°C	-40...+85°C

*Target power consumption - is a power consumption for calculation of the system of heat-removal from the module.

Actual power consumption depends on the load and the executed application and can be less than the specified value

**Operating temperature range depends on the device version